

HERCROM40G2**Appendix A - Mechanical****CAL000-B**

Ver 1.2

CALYPSO

Department: Application Specific Product / Wireless Communication Systems

	Originator	Approval	Approval
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Date	25 - February- 2000		
Signature			

HISTORY

Version	Date	Author	Notes
1.0	25 – Feb - 2000	Rodolphe Servato	1
1.1	19 – June - 2002	Rodolphe Servato	2
1.2	19 – July- 2002	Rodolphe Servato	3

Notes:

1. Creation of document.
2. Update Ch JTAG identification code (update field definition and link reference to the CAL207 spec), update Ch die identification code, update Ch A.2.1 (add C035 part numbers), remove Ch A.2.2 (TI Lead-frame numbers)
3. Update TU reference codes (ch A.2.1).

SUMMARY

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A.1 REFERENCE DOCUMENTS

The version number of a document is related to the version used for the CALYPSO project. This appendix contains ... of the CAL000 rev 0.1 specification.

A.2 MECHANICAL CHARACTERISTICS

A.2.1 TI reference codes

Device C05 / GHH package: PD741xxxGHH
 Device C035 / GHH package: PD751xxxGHH

A.2.2 JTAG identification code

The chip JTAG ID code is available either through the JTAG Test Access Port (IDCODE instruction) or in a MCU memory mapped register.

Value for CALYPSO JTAG ID code is given in Register mapping specification (CAL207)

Read access on MCU Rhea bus:

@FFFE:F000-FFFE:F001	↔	Device ID code part
@FFFE:F002-FFFE:F003	↔	Device code version

CPU (LEAD2+ARM7) subchip JTAG ID is given in Register mapping specification (CAL207)

Read access on MCU Rhea bus:

@FFFF:FE00-FFFF:FE01	↔	ARM ID code
@FFFF:FE02-FFFF:FE03	↔	cDSP ID code

Note: TI manufacturer code is not included in the MCU memory mapped registers.

A.2.3 Die identification code

The Die ID is a 64 bits fuse based register, and is unique. This value is TI internal data.

Read access on MCU Rhea bus:

@FFFE:F010-FFFE:F011	↔	bit 15-0
@FFFE:F012-FFFE:F013	↔	bit 31-16
@FFFE:F014-FFFE:F015	↔	bit 47-32
@FFFE:F015-FFFE:F016	↔	bit 63-48

A.2.4 Packaging (179GHH μ StarBGA)

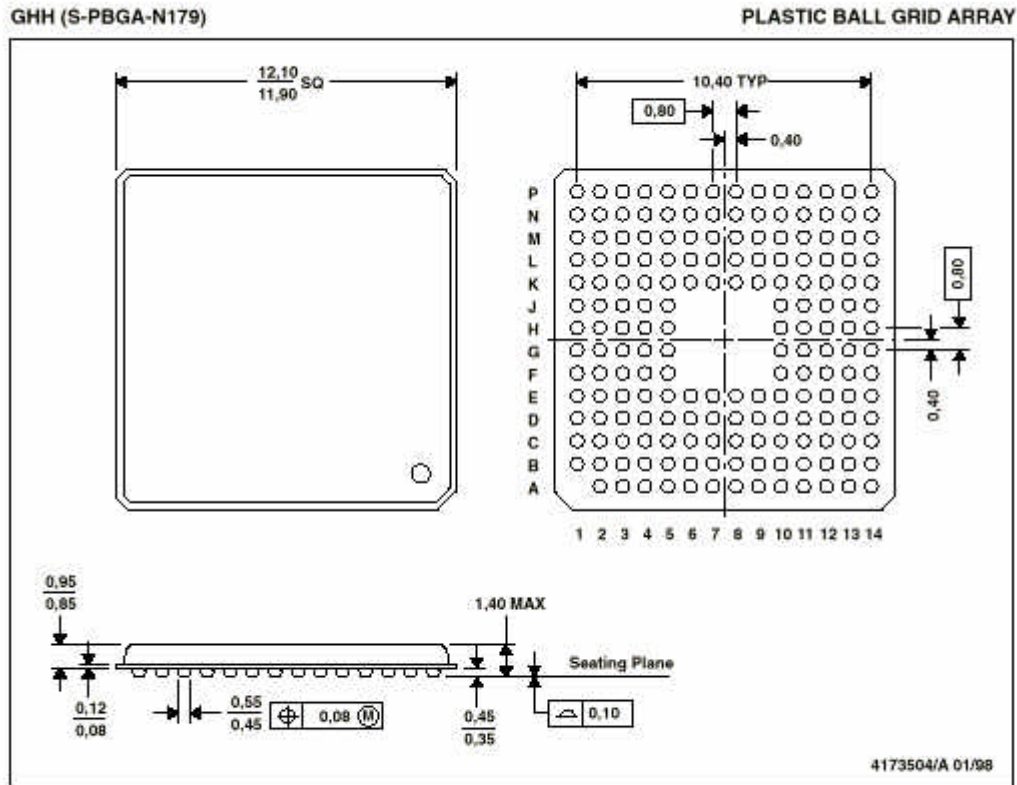
179 pins Micro STAR Ball Grid Array

Pitch: 0.80 mm.

Height: 1.40 mm.

SQ size: 12.00x12.00 mm².

MFBG058 - JANUARY 1998



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Micro Star[™] BGA configuration